

DOUBLE SIDED LAPPING/POLISHING MACHINE

双面研磨/抛光机YJ-16B5L/PE

本机器适用于硅片、石英晶片、宝石片、光学水晶、光学玻璃、铌酸锂、陶瓷片、玻璃及其它硬脆材料的双面精密研磨加工。

The machine is suitable for double-side precision lapping and polishing of silicon wafer, crystal quartz wafer, sapphire wafer, optical crystal, optical glass, lithium niobium acid, ceramic wafer, and other hard and fragile materials.



蓝宝石圆片



蓝宝石方片

设备特点

- 机器采用双电机驱动，游星轮在上下盘之间做行星运动，工件上下表面同时均匀研磨/抛光；
- 盘面操作高度控制在1050mm以内，增加机器的稳定性，适合操作；
- 内齿圈、太阳轮同步升降并采用点动操作方式；
- 上盘装置增加机械的安全装置，在摆片、维修等状态下不会因突然故障而下降，增加了安全性；
- 可实现游星轮的正、反转；通过游星轮正转和反转，实现盘面的修磨。

MAIN TECHNICAL FEATURES

- Two motors. Carriers rotate between upper and lower plates. Both sides of work pieces can be evenly lapped.
- User-friendly operation. The height of operation panel is within 1050mm.
- Ring gear and sun gear position is adjustable by jog operation.
- Mechanical safety device prevents upper plate from falling down.
- Ring gear and sun gear speed is adjustable to realize carrier rotation direction changing. It will realize plate conditioning.

主要技术参数 MAIN TECHNICAL SPECIFICATIONS

项目/Items	规格/Specs
上、下盘尺寸(Upper, lower plate size)	柱销齿(Dowel pin tooth): $\phi 1140 \times \phi 375 \times 45$ mm 渐开线齿(Involute gear): $\phi 1128 \times \phi 362 \times 50$ mm
工件厚度(Thickness of workpiece)	最大(Max):35 mm 最小(Min):0.4 mm
工件直径(Dimensions of workpiece)	最大(Max): $\phi 380$ mm
下盘转速(Lower plate rotational speed)	0 ~ 55rpm
游星轮数量(Number of Planet gears)	5
上盘主气缸行程(Upper plate cylinder stroke)	450 mm
齿圈抬升行程(Up and down stroke of gear ring)	30 mm
上、下盘电机(Upper, Lower plate motor)	3相(phase) 7.5 kw 1450 r/min
砂泵电机(Gear ring motor)	250 W
外形尺寸(Size L×W×H)	1970×1765×2670 mm
机器重量(Weight)	~ 4200 Kg